

Features

- 18 dB Gain at 2000 MHz
- 32.5 dBm P1dB at 2000 MHz
- 49 dBm Output IP3 at 2000 MHz
- MTTF > 100 Years
- Two Power Supplies

Description

The ASX621, a power amplifier MMIC, has a high linearity, high gain, and high efficiency over a wide range of frequency, being suitable for use in both receiver and transmitter of telecommunication systems up to 3 GHz. The amplifier is available in a SOIC8 package and passes through the stringent DC, RF, and reliability tests.



Package Style: SOIC8

Typical Performance

(Supply Voltage = Device Voltage, $T_A = +25\text{ }^\circ\text{C}$, $Z_0 = 50\ \Omega$)

Parameters	Units	Typical							
Frequency	MHz	900	2000	2450	900	2000	2450	2700	
Gain	dB	30.0	18.0	13.0	30.0	18.0	13.0	16.0	
S11	dB	-17.0	-14.0	-9.0	-17.0	-14.0	-9.0	-12.0	
S22	dB	-7.5	-14.0	-10.0	-7.5	-14.0	-10.0	-15.0	
Output IP3 ¹⁾	dBm	45	47	46	48	49	48	48	
Noise Figure	dB	11.0	5.5	6.8	11.5	5.6	7.0	5.9	
Output P1dB	dBm	32.0	31.5	32.0	33.0	32.5	33.0	33.0	
Current	mA	930			1150				
Device Voltage	V	+4.6			+5				

1) OIP3 measured with two tones at an output power of +14 dBm/tone separated by 1 MHz.

Product Specifications

Parameters	Units	Min	Typ	Max
Testing Frequency	MHz		2000	
Gain	dB	17.0	18.0	
S11	dB		-14	
S22	dB		-14	
Output IP3	dBm	47	49	
Noise Figure	dB		5.6	6.0
Output P1dB	dBm	31.5	32.5	
Current	mA	1050	1150	1250
Device Voltage	V		+5	

Absolute Maximum Ratings

Parameters	Rating
Operating Case Temperature	-40 to +85 °C
Storage Temperature	-40 to +150 °C
Device Voltage	+6 V
Operating Junction Temperature	+150 °C
Input RF Power (CW, 50 Ω matched) ¹⁾	+25 dBm
Thermal Resistance	10 °C/W

The operation of this device in excess of any of these limits may cause permanent damage.

* Refer to the max. input RF power data at http://www.asb.co.kr/pdf/Maximum_Input_Power_Analysis.pdf. The max. input RF power, in principle, depends upon application frequency, matching circuit, and device voltage.

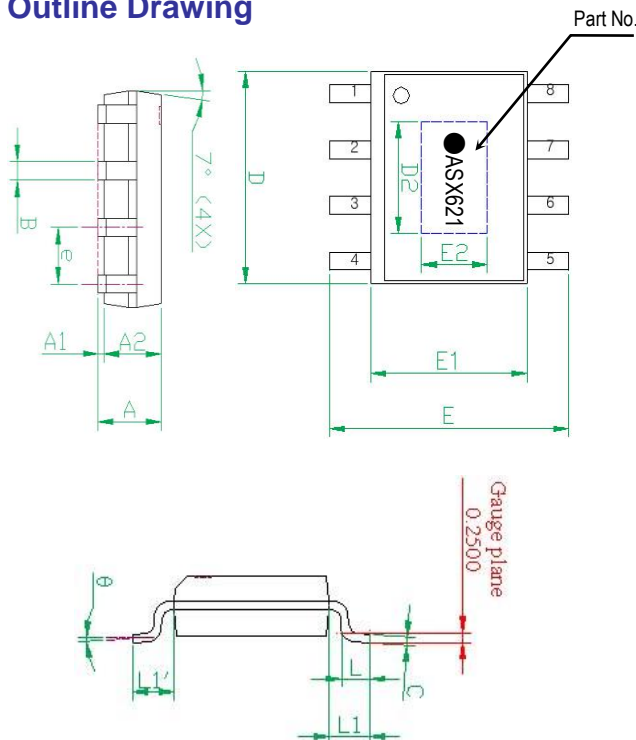
Application Circuit

- CDMA
- GSM
- WCDMA
- WLAN
- LTE (2620 ~ 2690 MHz)
- WiMAX
- Others (1200 ~ 1400 MHz)

Pin Configuration

Pin No.	Function
1	2nd stage RF IN
2	1st stage RF OUT
3,5,8	GND
4	1st stage RF IN
6,7	2nd stage RF OUT

Outline Drawing

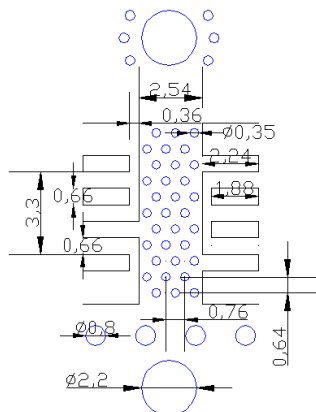


Symbols	Dimensions (In mm)		
	MIN	NOM	MAX
A	1.40	1.50	1.60
A1	0.00	---	0.10
A2	---	1.45	---
B	0.33	---	0.51
C	0.19	---	0.25
D	4.80	---	5.00
D2	3.20	3.30	3.40
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
E2	2.30	2.40	2.50
e	---	1.27	---
L	0.40	---	1.27
y	---	---	0.10
θ	0°	---	8°
L1-L1'	---	---	0.12
L1	1.04REF		

Pin No.	Function	Pin No.	Function.
1	2nd stage RF IN	5	GND
2	1st stage RF OUT	6	2nd stage RF OUT
3	GND	7	2nd stage RF OUT
4	1st stage RF IN	8	GND

Note: 1. Backside metal paddle is RF and DC ground.

Mounting Recommendation (In mm)



- Note:**
1. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
 2. To ensure reliable operation, device ground paddle-to-ground pad soldering is critical.
 3. Add mounting screws near the part to fasten the board to a heat sink. Ensure that the ground / thermal via region contacts the heat sink.
 4. A proper heat dissipation path underneath the area of the PCB for the mounted device is strictly required for proper thermal operation. Damage to the device can result from inappropriate heat dissipation.

ESD Classification

HBM	Class 1B Voltage Level: 500 V ~ 1000 V
MM	Class A Voltage Level: < 200 V

CAUTION: Gallium Arsenide Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices

Moisture Sensitivity Level (MSL)

Level 3 at 260 °C reflow

APPLICATION CIRCUIT

CDMA Rx

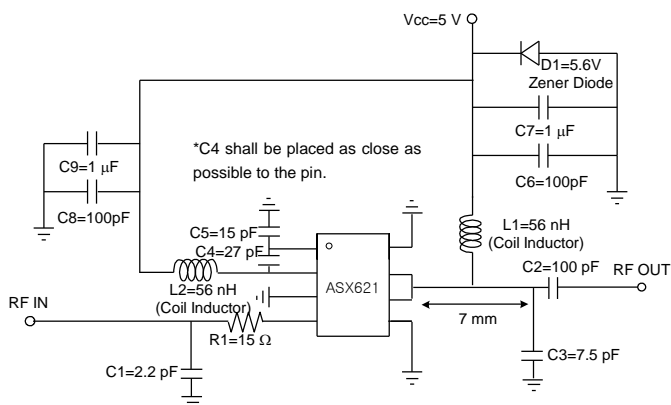
824 ~ 849 MHz

+5 V

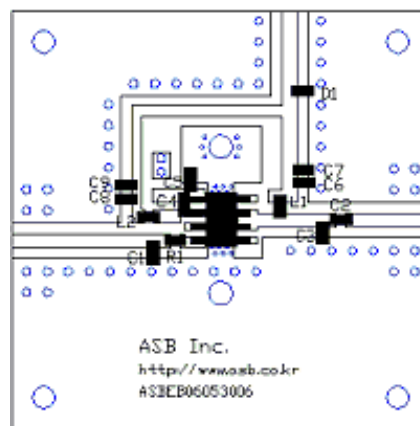
Frequency (MHz)	824 ~ 849
Magnitude S21 (dB)	28.0
Magnitude S11 (dB)	-14
Magnitude S22 (dB)	-8
Output P1dB (dBm)	32.5
Output IP3 ¹⁾ (dBm)	47
Noise Figure (dB)	11.0
Device Voltage (V)	+5
Current (mA)	1150

1) OIP3 is measured with two tones at an output power of +15 dBm/tone separated by 1 MHz.

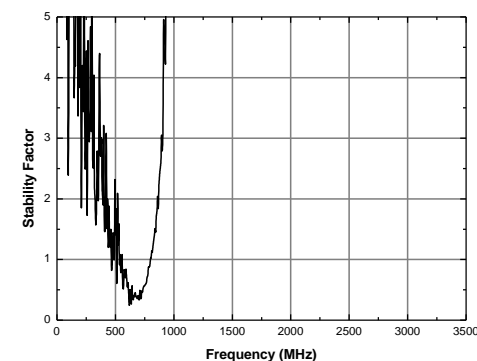
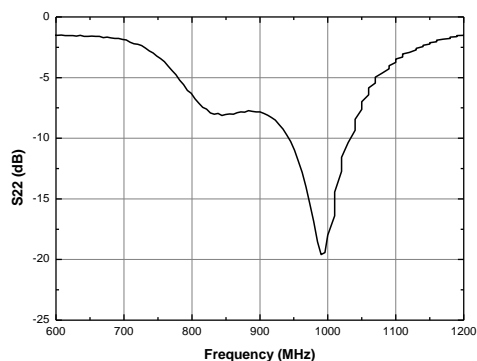
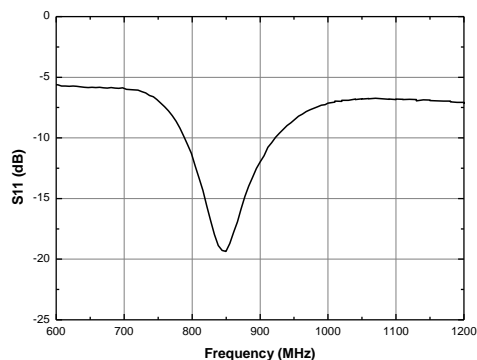
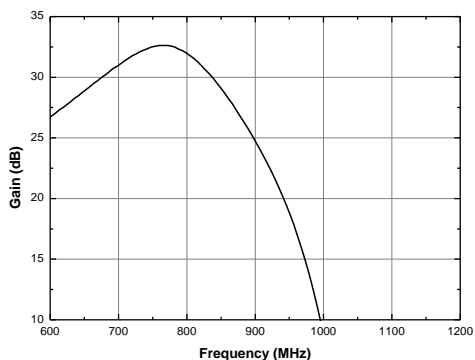
Schematic



Board Layout (FR4, 40x40 mm², 0.8T)



S-parameters



APPLICATION CIRCUIT

CDMA Tx, GSM

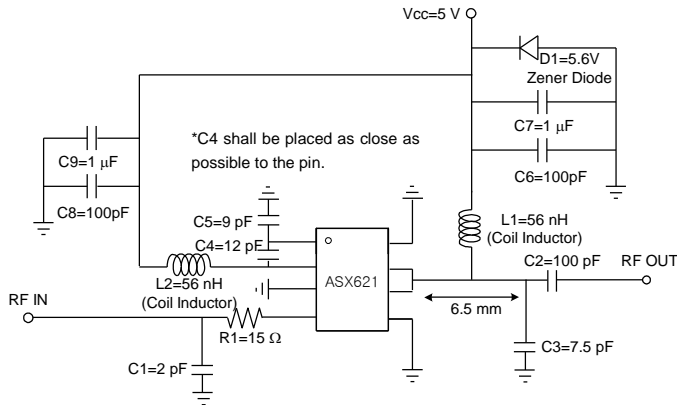
869 ~ 960 MHz

+5 V

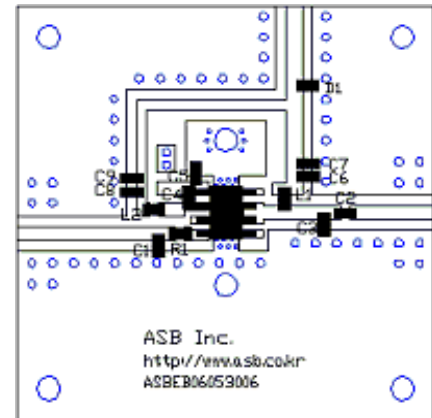
Frequency (MHz)	869	960
Magnitude S21 (dB)	31.0	26.0
Magnitude S11 (dB)	-13.0	-18.0
Magnitude S22 (dB)	-8.0	-7.5
Output P1dB (dBm)	32.5	32.5
Output IP3 ¹⁾ (dBm)	47	48
Noise Figure (dB)	11.0	11.0
Device Voltage (V)	+5	+5
Current (mA)	1150	1150

1) OIP3 is measured with two tones at an output power of +15 dBm/tone separated by 1 MHz.

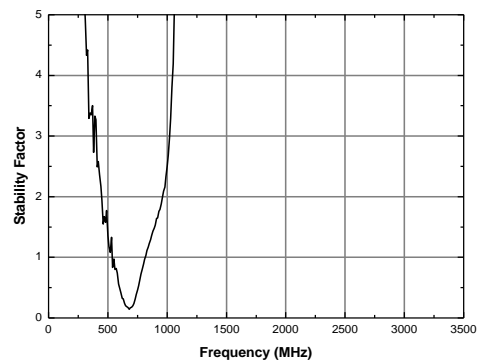
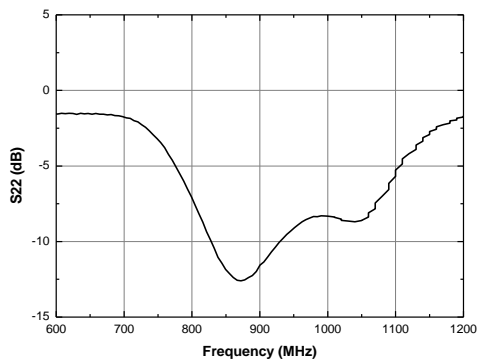
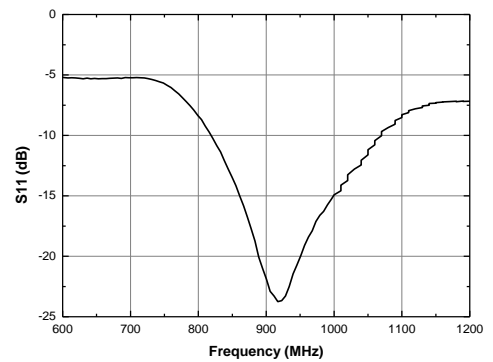
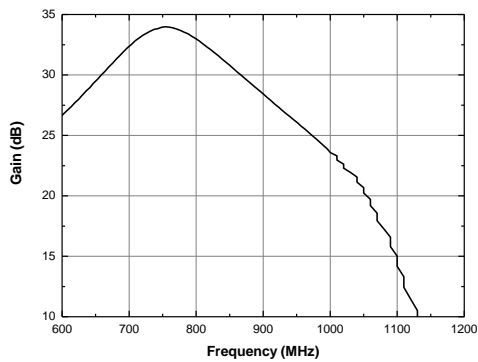
Schematic



Board Layout (FR4, 40x40 mm², 0.8T)



S-parameters



APPLICATION CIRCUIT

WCDMA Rx

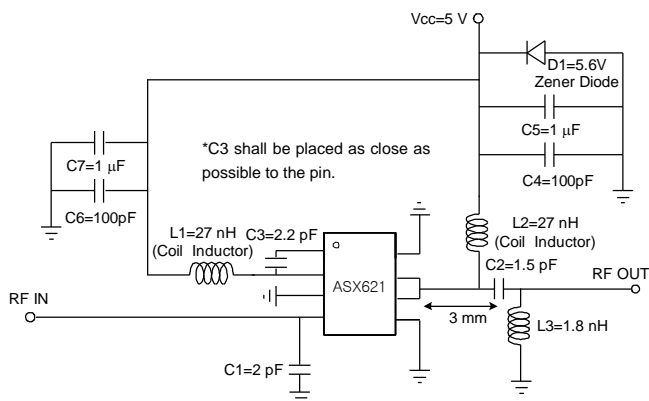
1920 ~ 1980 MHz

+5 V

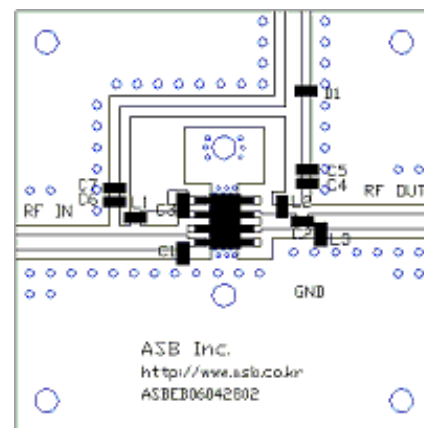
Frequency (MHz)	1920 ~ 1980
Magnitude S21 (dB)	18.0
Magnitude S11 (dB)	-14
Magnitude S22 (dB)	-14
Output P1dB (dBm)	32.5
Output IP3 ¹⁾ (dBm)	50
Noise Figure (dB)	5.6
Device Voltage (V)	+5
Current (mA)	1150

1) OIP3 is measured with two tones at an output power of +14 dBm/tone separated by 1 MHz.

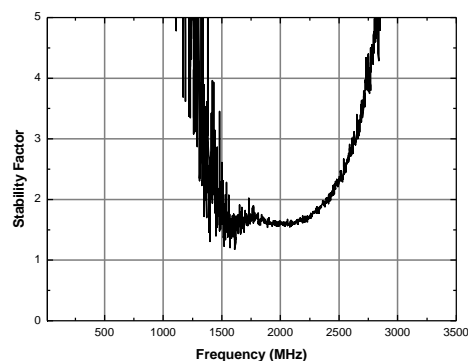
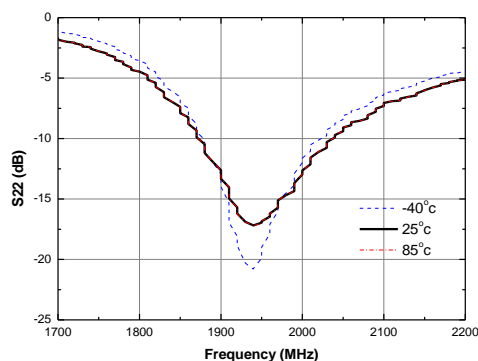
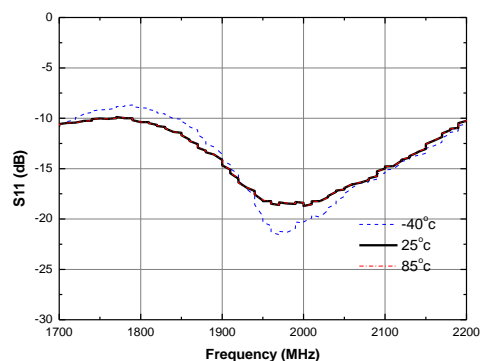
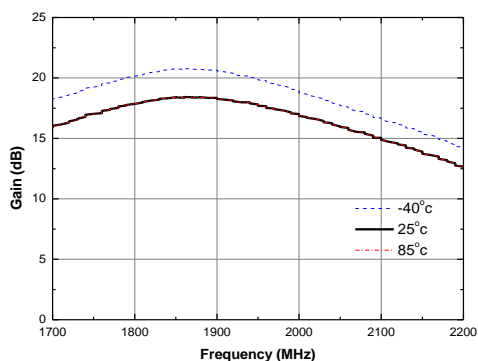
Schematic



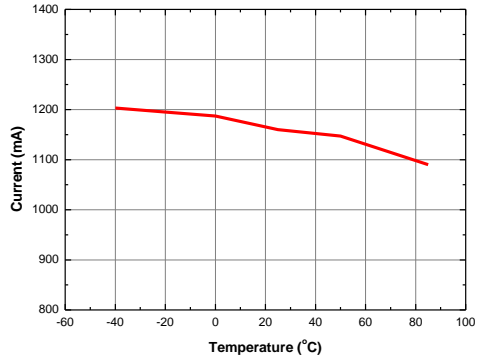
Board Layout (FR4, 40x40 mm², 0.8T)



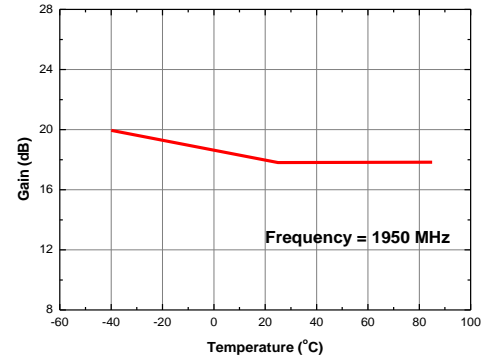
S-parameters



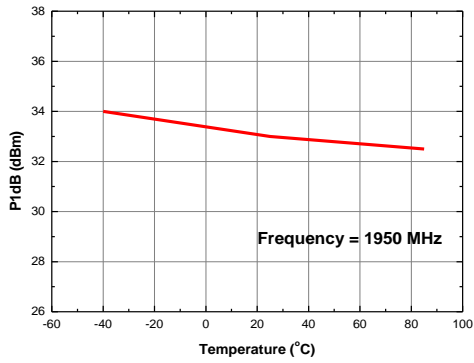
Current vs. Temperature



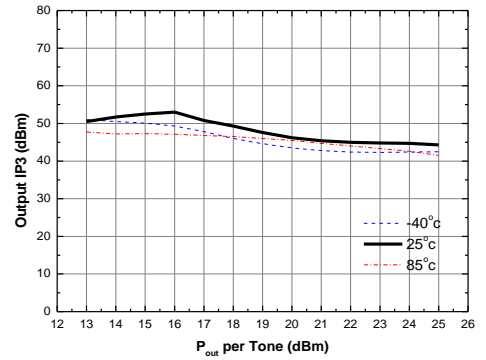
Gain vs. Temperature



P1dB vs. Temperature



Output IP3 vs. Tone Power (Frequency = 1950 MHz)



APPLICATION CIRCUIT

WCDMA Tx

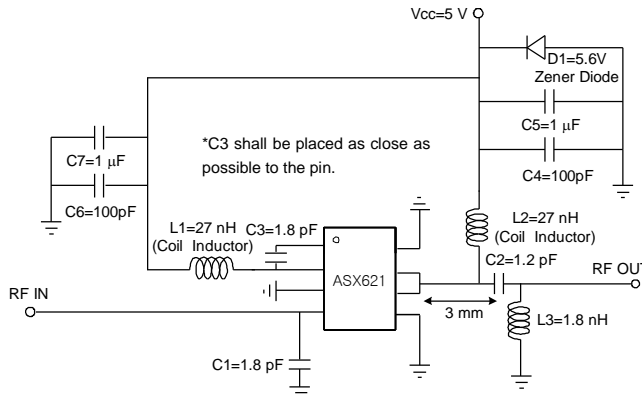
2110 ~ 2170 MHz

+5 V

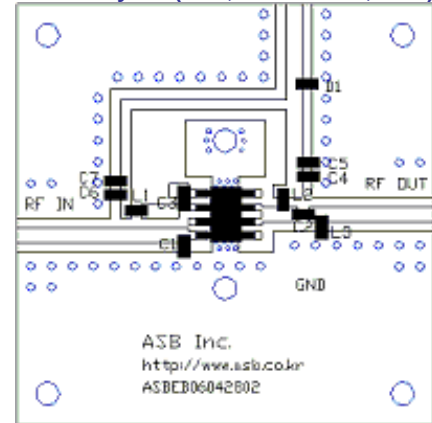
Frequency (MHz)	2110 ~ 2170
Magnitude S21 (dB)	17.0
Magnitude S11 (dB)	-15
Magnitude S22 (dB)	-13
Output P1dB (dBm)	32.5
Output IP3 ¹⁾ (dBm)	50
Noise Figure (dB)	5.6
Device Voltage (V)	+5
Current (mA)	1150

1) OIP3 is measured with two tones at an output power of +14 dBm/tone separated by 1 MHz.

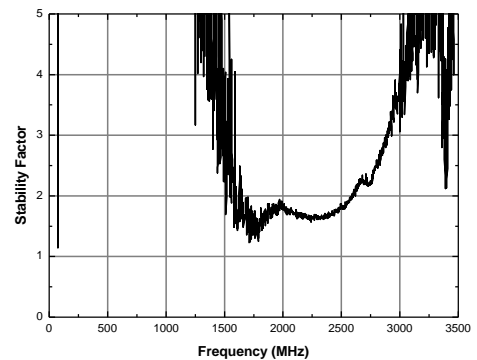
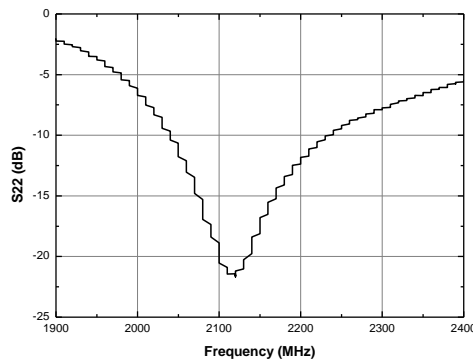
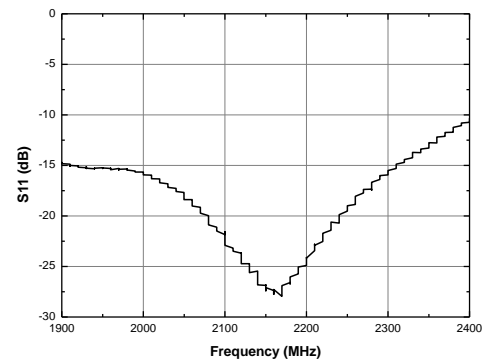
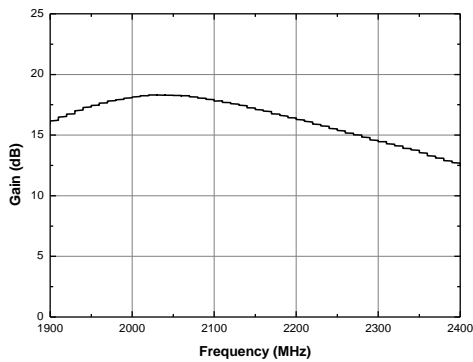
Schematic



Board Layout (FR4, 40x40 mm², 0.8T)



S-parameters



APPLICATION CIRCUIT

WLAN

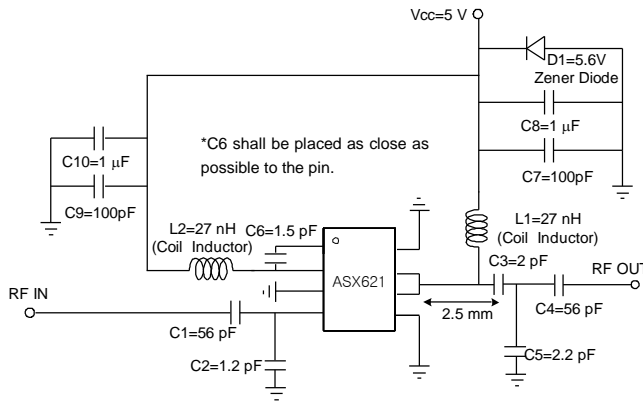
2400 ~ 2500 MHz

+5 V

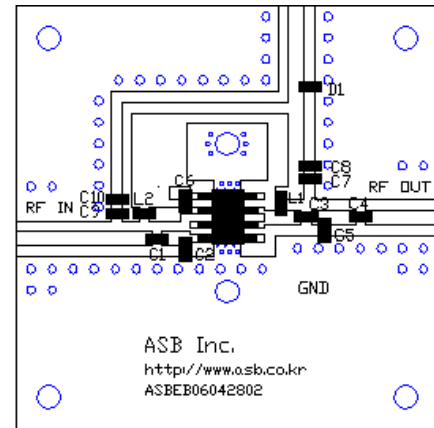
Frequency (MHz)	2400 ~ 2500
Magnitude S21 (dB)	13.0
Magnitude S11 (dB)	-9
Magnitude S22 (dB)	-10
Output P1dB (dBm)	33
Output IP3 ¹⁾ (dBm)	48
Noise Figure (dB)	7.0
Device Voltage (V)	+5
Current (mA)	1150

1) OIP3 is measured with two tones at an output power of +14 dBm/tone separated by 1 MHz.

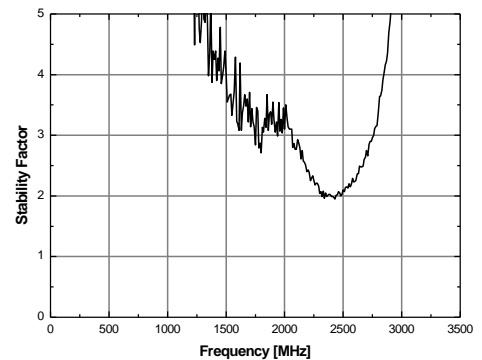
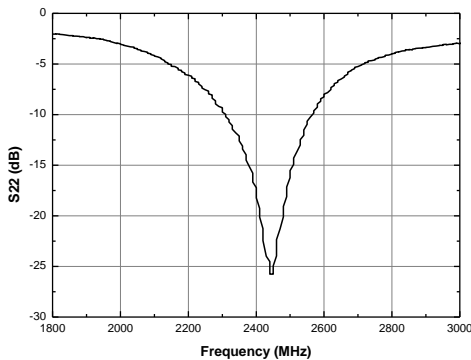
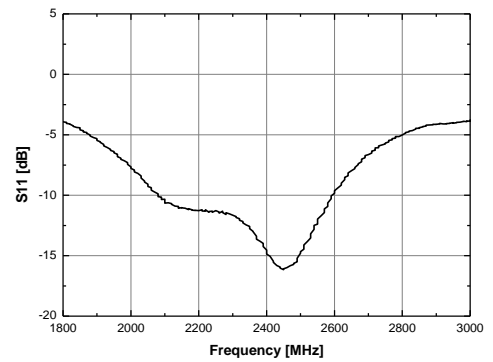
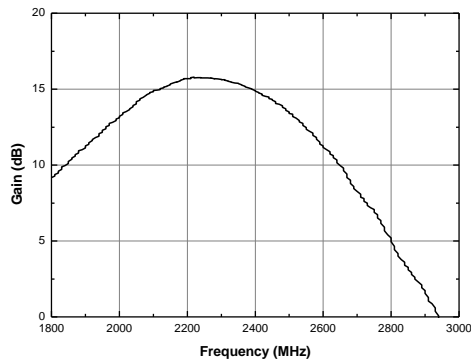
Schematic



Board Layout (FR4, 40x40 mm², 0.8T)



S-parameters



APPLICATION CIRCUIT

LTE

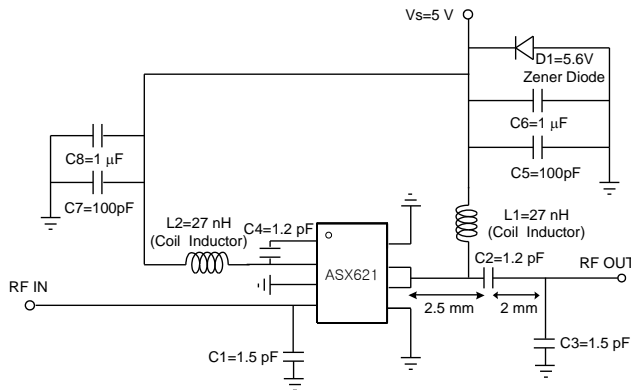
2620 ~ 2690 MHz

+5 V

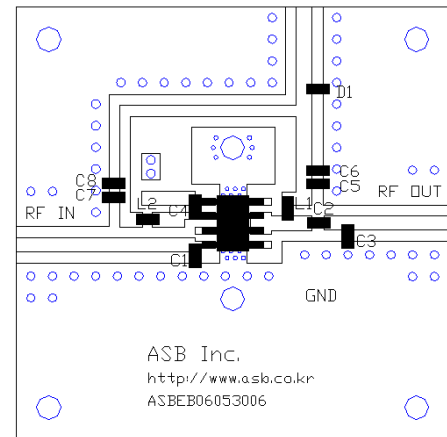
Frequency (MHz)	2620	2690
Magnitude S ₂₁ (dB)	16.9	15.5
Magnitude S ₁₁ (dB)	-18	-18
Magnitude S ₂₂ (dB)	-12	-8
Output P _{1dB} (dBm)	33	33
Output IP ₃ ¹⁾ (dBm)	48	49
Noise Figure (dB)	5.5	5.4
Device Voltage (V)	+5	
Current (mA)	1150	

1) OIP₃ is measured with two tones at an output power of +16 dBm/tones separated by 1 MHz.

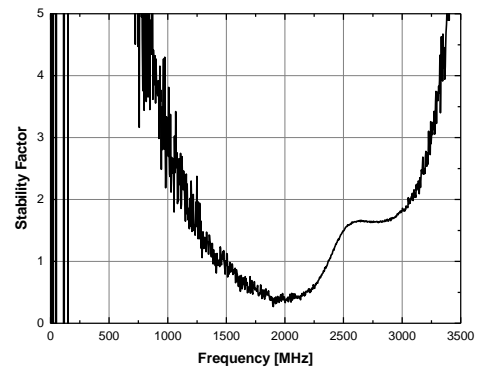
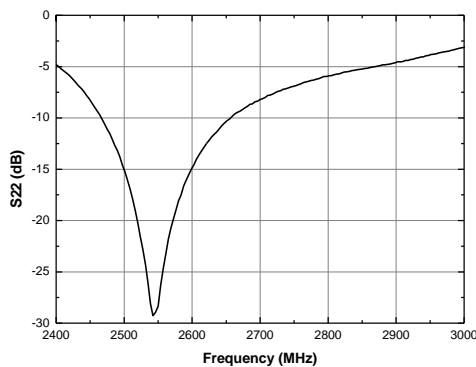
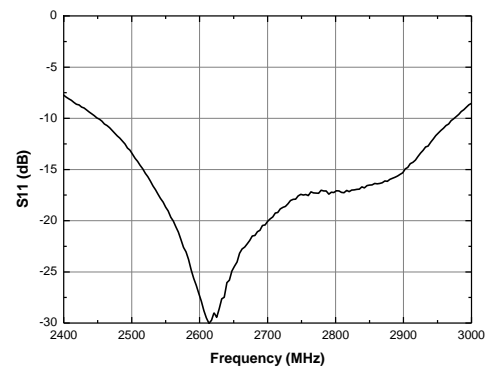
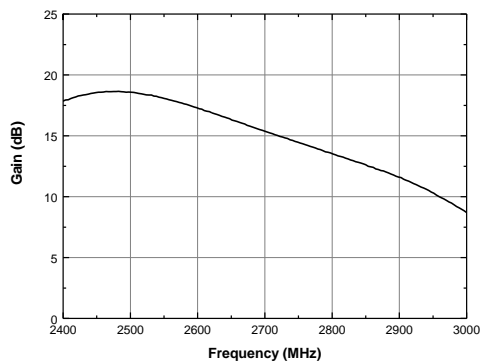
Schematic

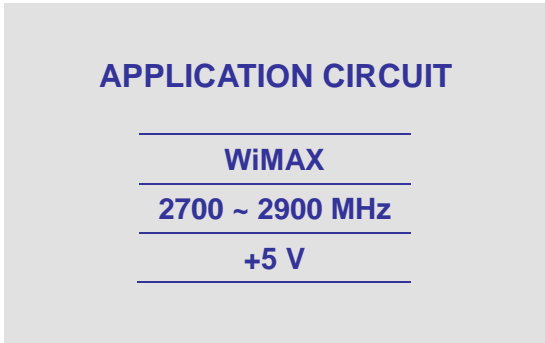


Board Layout (FR4, 40x40 mm², 0.8T)



S-parameters

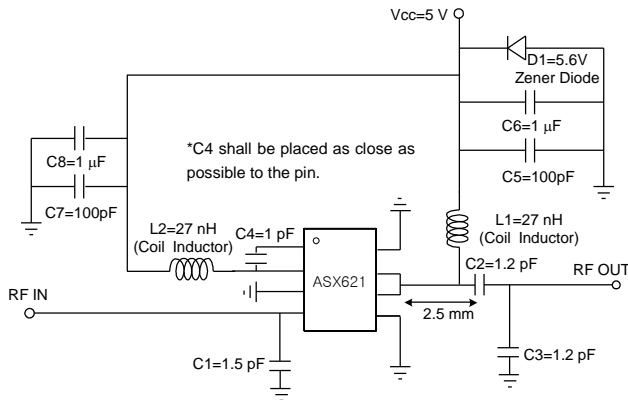




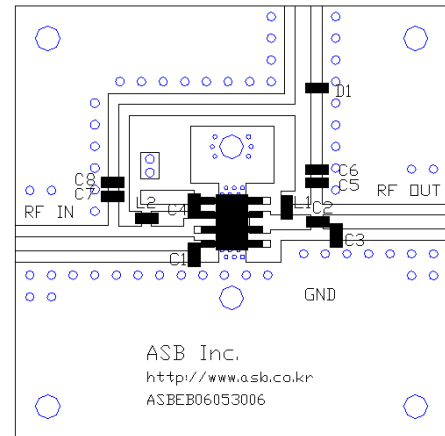
Frequency (MHz)	2700	2900
Magnitude S21 (dB)	16.0	14.0
Magnitude S11 (dB)	-12	-12
Magnitude S22 (dB)	-15	-15
Output P1dB (dBm)	33	
Output IP3 ¹⁾ (dBm)	48	
Noise Figure (dB)	5.9	
Device Voltage (V)	+5	
Current (mA)	1150	

1) OIP3 is measured with two tones at an output power of +15 dBm/tone separated by 1 MHz.

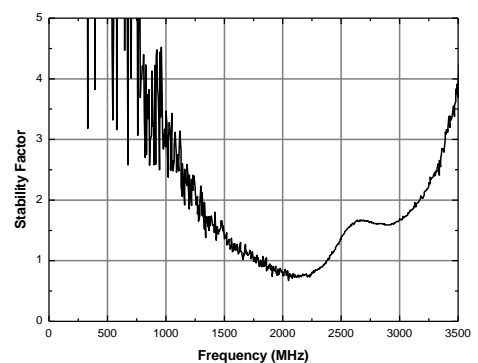
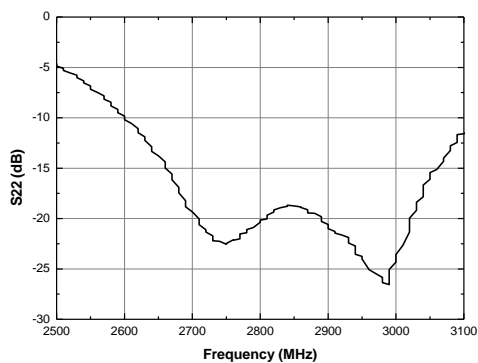
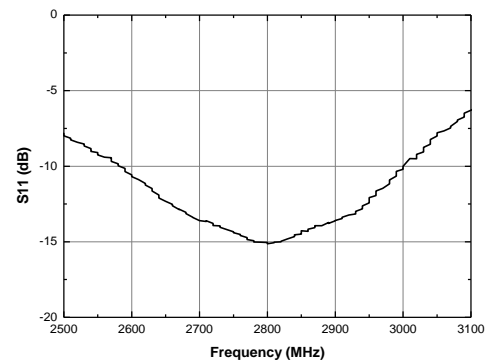
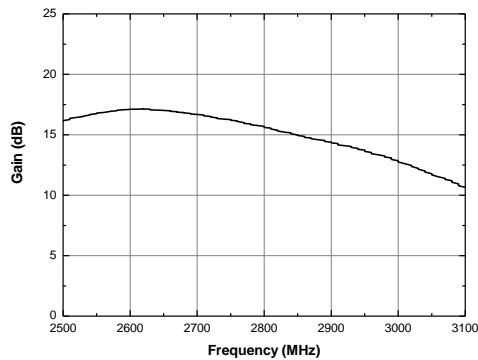
Schematic



Board Layout (FR4, 40x40 mm², 0.8T)



S-parameters



APPLICATION CIRCUIT

Others

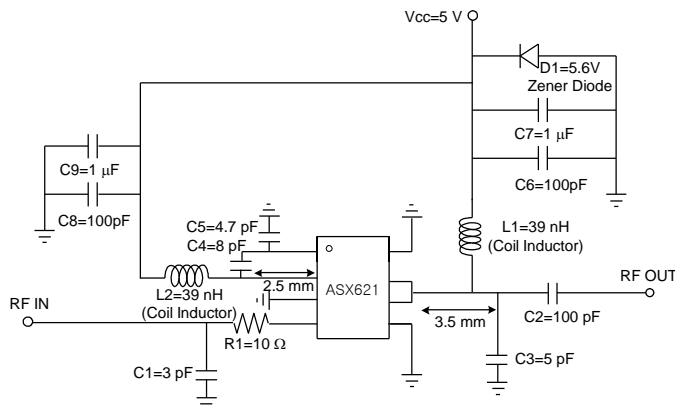
1200 ~ 1400 MHz

+5 V

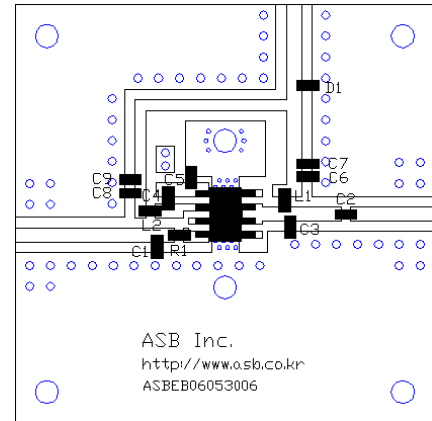
Frequency (MHz)	1200	1300	1400
Magnitude S21 (dB)	25.5	23.0	20.0
Magnitude S11 (dB)	-14	-12	-7
Magnitude S22 (dB)	-10	-9	-7
Output P1dB (dBm)	31.0	32.5	31.0
Output IP3 ¹⁾ (dBm)	48	48	47
Noise Figure (dB)	9.5	9.5	9.5
Device Voltage (V)	+5	+5	+5
Current (mA)	1150	1150	1150

1) OIP3 is measured with two tones at an output power of +14 dBm/tone separated by 1 MHz.

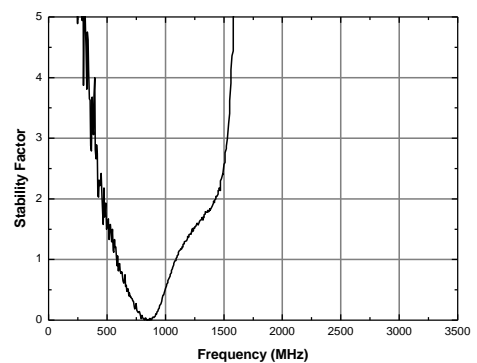
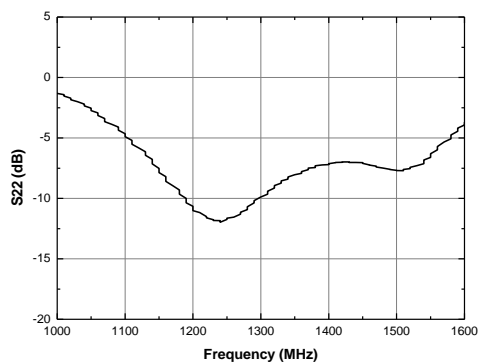
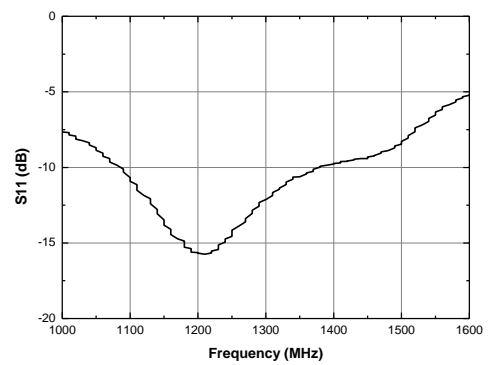
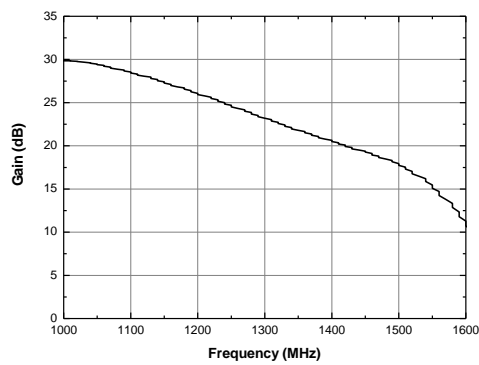
Schematic



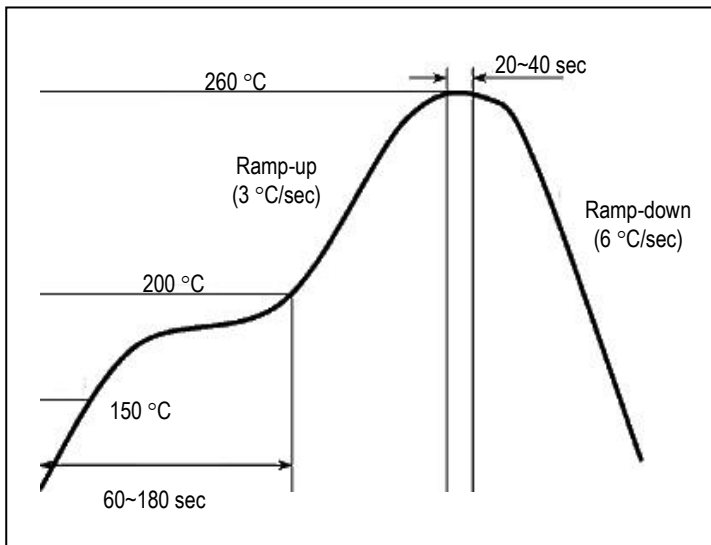
Board Layout (FR4, 40x40 mm², 0.8T)



S-parameters



Recommended Soldering Reflow Profile



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